

	Type	Hits	Search Text	DBs
1	BRS	18	((polish\$3 with pad) same ((substrate adj holder) or support or hold\$3 or platen or workpiece or substrate or wafer) same (glu\$3 or adhes\$4) same (layer or coat\$3)) and cur\$4 and expos\$4 and (photomask or mask)	USPAT; EPO; JPO; DERWENT; IBM_TDB
2	BRS	5	((polish\$3 with pad) same ((substrate adj holder) or support or hold\$3 or platen or workpiece or substrate or wafer) same (glu\$3 or adhes\$4) same (layer or coat\$3) same expos\$4) and (cure or curing or curable) and (photomask or mask)	USPAT; EPO; JPO; DERWENT; IBM_TDB
3	BRS	37	(polish\$3 with pad) and ((substrate adj holder) or support or hold\$3 or platen or workpiece or substrate or wafer) same (glu\$3 or adhes\$4 or resin\$3 or polyimide) same (layer or coat\$3) same expos\$4) and (cure or curing or curable) and (photomask or mask)	USPAT; EPO; JPO; DERWENT; IBM_TDB
4	IS&R	23	((("3875703") or ("3959935") or ("4558542") or ("5109638") or ("5341609") or ("5384988") or ("5470362") or ("5624304") or ("5921853") or ("6036579") or ("6036586"))).PN.	USPAT; EPO; JPO; DERWENT; IBM_TDB
5	BRS	30	((polish\$3 with pad) same remov\$3) and ((glu\$3 or adhes\$4 or resin\$3 or polyimide) same (layer or coat\$3) same expos\$4) and (cure or curing or curable) and (photomask or mask)	USPAT; EPO; JPO; DERWENT; IBM_TDB
6	BRS	8	(polish\$3 with pad) and ((adhesive or adhesion or glue or gluing or resinous or resin or polyimide) same (release or removal or removing or releasabl\$1) same (exposure or expos\$4) same (radiation or photolithographically or photolithography or photoexpos\$3))	USPAT; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
7	BRS	531	(passivat\$3 or (plasma same (water or "H.sub.2.O") same (oxygen or "O.sub.2"))) and ((remov\$3 or etch or eliminat\$3) same (chlorine or "Cl.sub.2")) and ((polymer or photoresist or resist) same pattern) and (metal\$3 same (pattern\$3 or structures))	USPAT; EPO; JPO; DERWENT; IBM_TDB
8	BRS	56	(passivat\$3 or (plasma same (water or "H.sub.2.O") same (oxygen or "O.sub.2"))) and ((remov\$3 or etch or eliminat\$3) same (chlorine or "Cl.sub.2") same (temperature or heat\$3 or anneal\$3 or (thermal with treat\$3)) same (polymer or photoresist or resist) same pattern\$3) and (metal\$3 same (pattern\$3 or structures))	USPAT; EPO; JPO; DERWENT; IBM_TDB
9	BRS	18	((passivat\$3 or plasma) same (water or "H.sub.2.O") same (oxygen or "O.sub.2")) and ((remov\$3 or etch or eliminat\$3) same (chlorine or "Cl.sub.2") same (temperature or heat\$3 or anneal\$3 or (thermal with treat\$3)) same (polymer or photoresist or resist) same pattern\$3) and (metal\$3 same (pattern\$3 or structures))	USPAT; EPO; JPO; DERWENT; IBM_TDB
10	IS&R	6	((("4767642") or ("4788798") or ("5551136")).PN.	USPAT; EPO; JPO; DERWENT; IBM_TDB
11	BRS	209	((polish\$3 with (pad or surface or substrate)) same remov\$3) and ((glu\$3 or adhes\$4 or resin\$3 or polyimide) same (layer or coat\$3) same expos\$4) and (cure or curing or curable) and (photomask or mask)	USPAT; EPO; JPO; DERWENT; IBM_TDB
12	BRS	4	((polish\$3 same remov\$3) same (glu\$3 or adhes\$4 or resin\$3 or polyimide or precursor or oligomer) same expos\$4 same (radiation or UV or excimer)) and (cure or curing or curable) and (photomask or mask) and (photolithograph\$6 or lithograph\$6)	USPAT; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
13	BRS	9	(polish\$3 same (pad or platen or substrate or surface) same (glu\$3 or adhes\$4 or resin\$3 or polyimide or precursor or oligomer) same expos\$4 same (radiation or UV or excimer)) and (cure or curing or curable) and (photomask or mask) and (photolithograph\$6 or lithograph\$6)	USPAT; EPO; JPO; DERWENT; IBM_TDB
14	BRS	2	(polish\$3 same remov\$3 same (glu\$3 or adhes\$4 or resin\$3 or stick\$5) same expos\$4 same (radiation or UV or excimer) same (substrate or surface or pad or wafer or platen)) and (cure or curing or curable or photocur\$4) and (photomask or mask) and ((photolithograph\$6 or lithograph\$6) same (apparatus or system))	USPAT; EPO; JPO; DERWENT; IBM_TDB
15	BRS	2	(polish\$4 adj pad) and (remov\$3 same (glu\$3 or adhes\$4 or resin\$3 or stick\$5 or polyimide or precursor or ((release or sacrificial) adj (layer or material))) same expos\$4 same (radiation or UV or excimer)) and (cure or curing or curable or photocur\$4) and (photomask or mask) and ((photolithograph\$6 or lithograph\$6) same (apparatus or system))	USPAT; EPO; JPO; DERWENT; IBM_TDB
16	BRS	3	(polish\$4 adj pad) and ((remov\$4 or pattern\$4) same (glu\$3 or adhes\$4 or resin\$3 or stick\$5 or polyimide or precursor or photoresist or ((release or sacrificial) adj (layer or material))) same expos\$4 same (radiation or UV or excimer)) and (cure or curing or curable or photocur\$4) and (photomask or mask) and ((photolithograph\$6 or lithograph\$6) same (apparatus or system))	USPAT; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
17	BRS	1	((polish\$4 adj pad) same (manufactur\$4 or mak\$4 or produc\$3)) and (pattern\$4 same (glu\$3 or adhes\$4 or resin\$3 or polyimide or precursor or photoresist or oligomer) same (expos\$4 or photoexpos\$3) same (radiation or UV or excimer)) and (cure or curing or curable or photocur\$4) and (photomask or mask) and ((photolithograph\$6 or lithograph\$6) same (apparatus or system))	USPAT; EPO; JPO; DERWENT; IBM_TDB
18	BRS	3	(polish\$4 adj pad) and (pattern\$4 same (glu\$3 or adhes\$4 or resin\$3 or polyimide or precursor or photoresist or oligomer) same (expos\$4 or photoexpos\$3) same (radiation or UV or excimer)) and (cure or curing or curable or photocur\$4) and (photomask or mask) and ((photolithograph\$6 or lithograph\$6) same (apparatus or system))	USPAT; EPO; JPO; DERWENT; IBM_TDB
19	BRS	9	(polish\$4 adj pad) and (pattern\$4 same (glu\$3 or adhes\$4 or resin\$3 or polyimide or precursor or photoresist or oligomer) same (expos\$4 or photoexpos\$3) same (radiation or UV or excimer)) and (cure or curing or curable or photocur\$4) and (photomask or mask) and (photolithograph\$6 or lithograph\$6)	USPAT; EPO; JPO; DERWENT; IBM_TDB
20	BRS	12	(polish\$4 adj pad) and (pattern\$4 same (glu\$3 or adhes\$4 or resin\$3 or polyimide or precursor or photoresist or oligomer or photopolymeriz\$5 or photocur\$4 or photomechanical) same (expos\$4 or photoexpos\$3) same (radiation or UV or excimer or light)) and (cure or curing or curable or photocur\$4) and (photomask or mask) and (photolithograph\$6 or lithograph\$6)	USPAT; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
21	IS&R	2	("5258236").PN.	USPAT; EPO; JPO; DERWENT; IBM_TDB
22	BRS	0	((polish\$3 with (pad or surface or substrate)) same remov\$3) and ((glu\$3 or adhes\$4 or resin\$3 or polyimide) same (layer or coat\$3) same expos\$4) and (cure or curing or curable) and ((photomask or mask) same (ceramic or metal or polymer\$2 or quartz) same shutter)	USPAT; EPO; JPO; DERWENT; IBM_TDB
23	BRS	2	(polish\$3 with (pad or surface or substrate or platen)) and ((glu\$3 or adhes\$4 or resin\$3 or polyimide or precursor or oligomer or photopolymeriz\$4 or polymer\$2) same (layer or coat\$3) same expos\$4) and (cure or curing or curable or photocur\$4) and ((photomask or mask) same (ceramic or metal or polymer\$2 or quartz) same shutter)	USPAT; EPO; JPO; DERWENT; IBM_TDB
24	BRS	3	(polish\$3 with (pad or surface or substrate or platen)) and ((glu\$3 or adhes\$4 or resin\$3 or polyimide or precursor or oligomer or photo\$1polymeriz\$4 or polymer\$2 or photosensitive or photoresist) same (layer or coat\$3) same expos\$4) and (cure or curing or curable or photo\$1cur\$4) and ((photomask or mask) same (ceramic or metal or polymer\$2 or quartz) same shutter)	USPAT; EPO; JPO; DERWENT; IBM_TDB
25	BRS	1	(polish\$4 adj pad) and (pattern\$4 same (glu\$3 or adhes\$4 or resin\$3 or polyimide or precursor or photoresist or oligomer or photo\$1polymeriz\$5 or photo\$1cur\$4 or photo\$1mechanical) same (expos\$4 or photo\$1expos\$3) same (radiation or UV or excimer or light)) and (cure or curing or curable or photo\$1cur\$4) and ((photomask or mask) same shutter) and (photolithograph\$6 or lithograph\$6)	USPAT; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
26	BRS	1	(polish\$4 adj pad) and (pattern\$4 same (glu\$3 or adhes\$4 or resin\$3 or polyimide or precursor or photoresist or oligomer or photo\$1polymeriz\$5 or photo\$1cur\$4 or photo\$1mechanical) same (expos\$4 or photo\$1expos\$3)) and (cure or curing or curable or photo\$1cur\$4) and ((photomask or mask) same shutter) and (photolithograph\$6 or lithograph\$6)	USPAT; EPO; JPO; DERWENT; IBM_TDB
27	BRS	1	(polish\$4 adj pad) and ((glu\$3 or adhes\$4 or resin\$3 or polyimide or precursor or photoresist or oligomer or photo\$1polymeriz\$5 or photo\$1cur\$4 or photo\$1mechanical or photosensitive) same (expos\$4 or photo\$1expos\$3)) and (cure or curing or curable or photo\$1cur\$4) and ((photomask or mask) same shutter) and (photolithograph\$6 or lithograph\$6)	USPAT; EPO; JPO; DERWENT; IBM_TDB
28	BRS	23	((glu\$3 or adhes\$4 or resin\$3 or polyimide or precursor or photoresist or oligomer or photo\$1polymeriz\$5 or photo\$1cur\$4 or photo\$1mechanical or photosensitive) same (expos\$4 or photo\$1expos\$3)) and (cure or curing or curable or photo\$1cur\$4) and ((photomask or mask) same shutter) and (photolithograph\$6 or lithograph\$6)	USPAT; EPO; JPO; DERWENT; IBM_TDB
29	IS&R	2	("6503693").PN.	USPAT; EPO; JPO; DERWENT; IBM_TDB
30	BRS	10	((polish\$3 with pad) same (glu\$3 or adhes\$4 or resin\$3 or polyimide) same (layer or coat\$3) same expos\$4 same (cur\$4 or photo\$1cur\$4 or imag\$4)) and (photomask or mask)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
31	BRS	165	(polish\$3 with pad) same manufacture same apparatus	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
32	IS&R	6	((("6290589") or ("4767642") or ("4788798")).PN.	USPAT; EPO; JPO; DERWENT; IBM_TDB
33	IS&R	2	("5551136").PN.	USPAT; EPO; JPO; DERWENT; IBM_TDB
34	BRS	6	(cur\$3 with (polymer\$2 or resist\$3)) and ((transfer\$4 with (imag\$4 or print\$4)) same adher\$4 same substrate same sublimat\$4)	USPAT; EPO; JPO; DERWENT; IBM_TDB
35	BRS	14	((polish\$3 with pad) same (glu\$3 or adhes\$6 or resin\$3 or polyimide) same (layer or coat\$3) same expos\$4 same (cur\$4 or photo\$1cur\$4 or imag\$4)) and (photomask or mask) and ((chang\$4 or degrad\$5 or alter\$4) same (adhesive\$6 or strength))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
36	BRS	12	((polish\$3 with pad) same (glu\$3 or adhes\$6 or resin\$3 or polyimide) same (layer or coat\$3 or film or form\$3 or deposit\$4) same expos\$4 same (cur\$4 or photo\$1cur\$4 or imag\$4)) and (photomask or mask or reticle) and ((chang\$4 or degrad\$5 or alter\$4 or less\$3 or reduc\$5 or lower\$4) same (adhesive\$6 or strength) same (irradiat\$4 or expos\$4 or cur\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
37	IS&R	1	("20010055939").PN.	USPAT; US-PGPUB
38	BRS	20	((polish\$3 with pad) same (glu\$3 or adhes\$6 or resin\$3 or polyimide) same (expos\$4 or irradiat\$4)) and (photomask or mask or reticle) and ((chang\$4 or degrad\$5 or alter\$4 or less\$3 or reduc\$5 or lower\$4) same (adhesive\$6 or strength) same (irradiat\$4 or expos\$4 or cur\$4 or photo\$2cur\$4) same (resist or photoresist or glu\$3 or resin\$4 or acrylic or adhesive or polyimide))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
39	IS&R	3	((("6210254") or ("5258236") or ("4063812")).PN.	USPAT; US-PGPUB
40	IS&R	1	("6716092").PN.	USPAT; US-PGPUB